



规格书编号

SPEC NO :

产品规格书

SPECIFICATION

CUSTOMER 客户: _____

PRODUCT 产品: _____ SAW RESONATOR _____

MODEL NO 型号: _____ R315M D11 _____

PREPARED 编制: _____ CHECKED 审核: _____

APPROVED 批准: _____ D A T E 日期: _____ 2011-6-20 _____

客户确认 CUSTOMER RECEIVED:		
审核 CHECKED	批准 APPROVED	日期 DATE

深圳市春宇无线有限公司
CY Wireless Technology Limited



1. SCOPE

This specification is applied to a SAW resonator designed for the stabilization of transmitters such as garage door openers and security transmitters.

2. ELECTRICAL SPECIFICATION

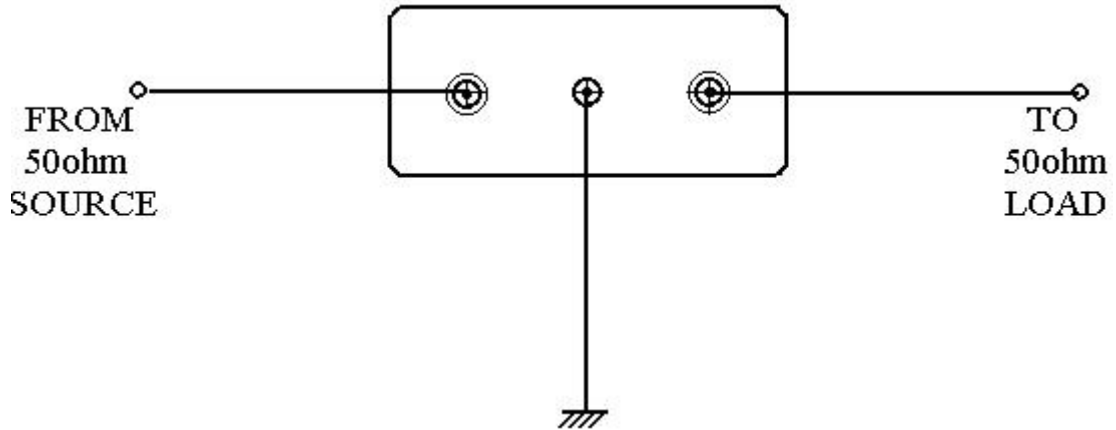
DC Voltage VDC	30V
AC Voltage Vpp	10V50Hz/60Hz
Operation temperature	-40°C to +85°C
Storage temperature	-45°C to +85°C
RF Power Dissipation	0dBm

2.2 Electronic Characteristics

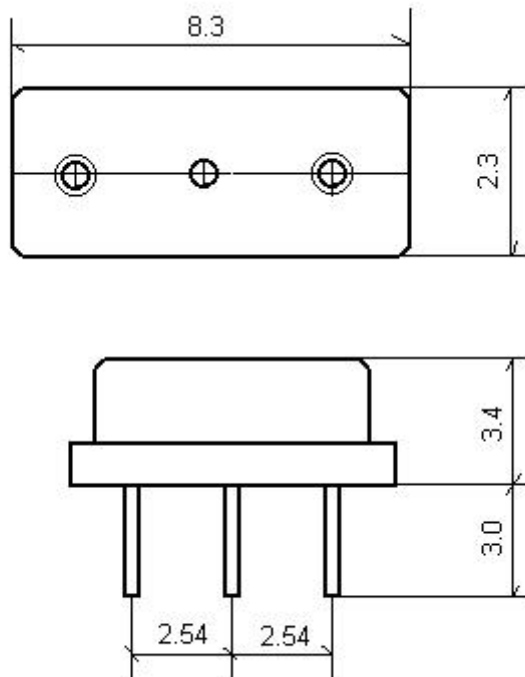
Item		Unites	Minimum	Typical	Maximum
Center Frequency		MHz	314.925	315.000	315.075
Insertion Loss		dB		1.5	2.2
Quality Factor Unload Q			8000	12800	
50 Ω Loaded Q			1000	2000	
Temperature	Turnover Temperature	°C	10	25	40
Stability	Freq.temp.Coefficient	ppm/°C ²		0.037	
Frequency Aging		ppm/yr		≤10	
DC. Insulation Resistance		MΩ	1.0		
RF Equivalent RLC Model	Motional Resistance R1	Ω		14	26
	Motional Inductance L1	μ H		109.28	
	Motional Capacitance C1	fF		2.3357	
Transducer Static Capacitance		pF		2.7	



3. TEST CIRCUIT



4. DIMENSION





5. ENVIRONMENTAL CHARACTERISTICS

5-1 High temperature exposure

Subject the device to +85 °C for 16 hours. Then release the resonator into the room conditions for 24 hours prior to the measurement. It shall fulfill the specifications in 2.2.

5-2 Low temperature exposure

Subject the device to -40°C for 16 hours. Then release the device into the room conditions for 24 hours prior to the measurement. It shall fulfill the specifications in 2.2.

5-3 Temperature cycling

Subject the device to a low temperature of -40 °C for 30 minutes. Following by a high temperature of +85 °C for 30 Minutes. Then release the device into the room conditions for 24 hours prior to the measurement. It shall meet the specifications in 2.2.

5-4 Resistance to solder heat

Dip the device terminals no closer than 1.5mm into the solder bath at 260°C ± 10°C for 10 ± 1 sec. Then release the device into the room conditions for 4 hours. The device shall meet the specifications in 2.2.

5-5 Solderability

Subject the device terminals into the solder bath at 245°C ± 5°C for 5s, More than 95% area of the terminals must be covered with new solder. It shall meet the specifications in 2.2.

5-6 Mechanical shock

Drop the device randomly onto the concrete floor from the height of 1m 3 times. the device shall fulfill the specifications in 2.2.

5-7 Vibration

Subject the device to the vibration for 1 hour each in x, y and z axes with the amplitude of 1.5 mm at 10 to 55 Hz. The device shall fulfill the specifications in 2.2.

6. REMARK

6.1 Static voltage

Static voltage between signal load & ground may cause deterioration & destruction of the component. Please avoid static voltage.

6.2 Ultrasonic cleaning

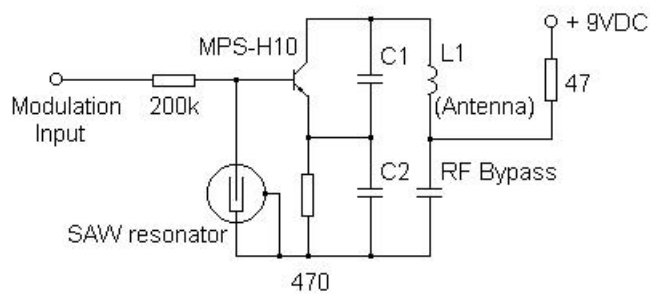
Ultrasonic vibration may cause deterioration & destruction of the component. Please avoid ultrasonic cleaning

6.3 Soldering

Only leads of component may be soldered. Please avoid soldering another part of component.

7. TYPICAL APPLICATION CIRCUITS

Typical low-power Transmitter Application



Typical Local Oscillator Application

